



## Material Content Data Sheet



<b>Sales Product Name</b>		IDH05S120	<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000622908						
<b>Package</b>		PG-TO220-2-1	<b>Weight*</b>		1970.68 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	siliconcarbide	409-21-2	3.465	0.18	0.18	1758	1758
leadframe	non noble metal	iron	7439-89-6	1.343	0.07		681	
	inorganic material	phosphorus	7723-14-0	0.403	0.02		204	
	non noble metal	copper	7440-50-8	1341.263	68.06	68.15	680611	681496
wire	non noble metal	aluminium	7429-90-5	0.683	0.03	0.03	347	347
encapsulation	organic material	carbon black	1333-86-4	9.070	0.46		4602	
	plastics	epoxy resin	-	99.768	5.06		50626	
	inorganic material	silicondioxide	60676-86-0	495.819	25.16	30.68	251598	306826
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7351	7351
plating	non noble metal	nickel	7440-02-0	0.198	0.01		100	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	100
solder	noble metal	silver	7440-22-4	0.105	0.01		53	
	non noble metal	tin	7440-31-5	0.084	0.00		42	
	non noble metal	lead	7439-92-1	3.994	0.20	0.21	2027	2122
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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